

WAFER CARRIER TRAY

ABSTRACT OF THE DISCLOSURE

A wafer carrier tray is integrally formed of a ceramic material having a bore, a coupling surface, and a carrying surface. The bore is formed in a center and extends therethrough from the top to the bottom for receiving an electrostatic chuck of a machine to fit therein. The coupling surface is formed on the bottom for coupling to the machine. The carrying surface is formed on the top and has a plurality of equally spaced carrier blocks arranged at locations adjacent to the bore and each including a support face located on a top and slanting downwards from outside to inside for supporting a wafer and two side faces located on opposite sides and slanting toward each other from outside to inside. The two side faces have top edges that are connected to two opposite side edges of the support face.

Fig. 4